

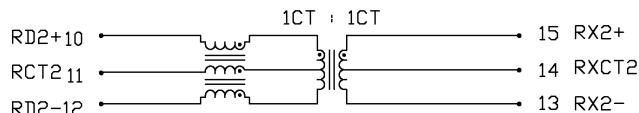
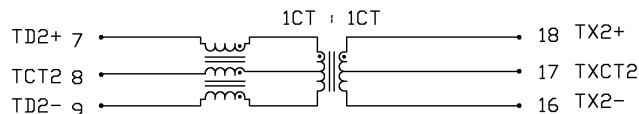
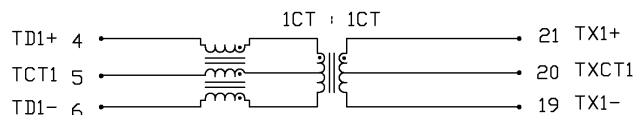
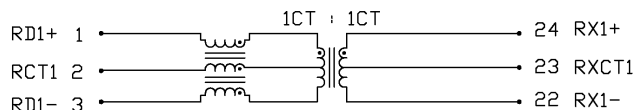
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CHIP SIDE

MEDIA SIDE

ELECTRICAL CHARACTERISTICS (<25°C)



NOTES:

1. THIS DESIGN CAN BE APPLIED TO EITHER 10/100 BASE T OR
1000 BASE T IF DESIRE.

URNS RATIO

Rx CHIP SIDE: MEDIA SIDE 1CT : 1CT
Tx CHIP SIDE: MEDIA SIDE 1CT : 1CT

OCL

MEDIA SIDE 350μH MIN.
@ 100kHz, 100mVrms
w/8mA DC BIAS

INSERTION LOSS

100kHz 1.2 dB MAX
1MHz TO 100MHz 1.0 dB MAX
125MHz 3.0 dB MAX

RETURN LOSS

1MHz-30MHz 18 dB MIN
30MHz-80MHz 12-20LOG(F/80MHz) dB MIN
100MHz 10 dB MIN

CROSSTALK

1MHz 55 dB MIN
10MHz-100MHz 55-24LOG(F/10MHz) dB MIN

DM TO CM REJECTION

2MHz 60 dB MIN
30MHz - 200MHz 40-22LOG(F/30MHz) dB MIN

HIPOT

PER HAND-WORK-03

ORIGINATED BY	DATE	TITLE	PART NO. / DRAWING NO.	STANDARD DIM.	[] METRIC DIM. AS REFERENCE
HO	10-26-05	ELECTRICAL SPECIFICATION	X558-5500-44	TOL. IN INCH	UNIT : INCH [mm] REV. : A
DRAWN BY	DATE		FILE NAME	.X	SCALE : N/A SIZE : A4
DQ Chen	10-26-05		X558550044A.DWG	.XX	PAGE : 2
				.XXX	

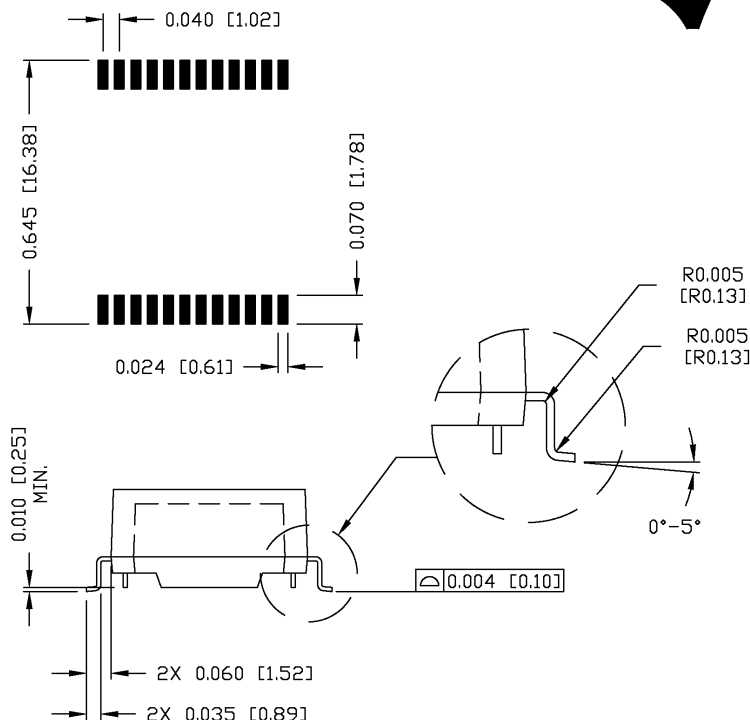
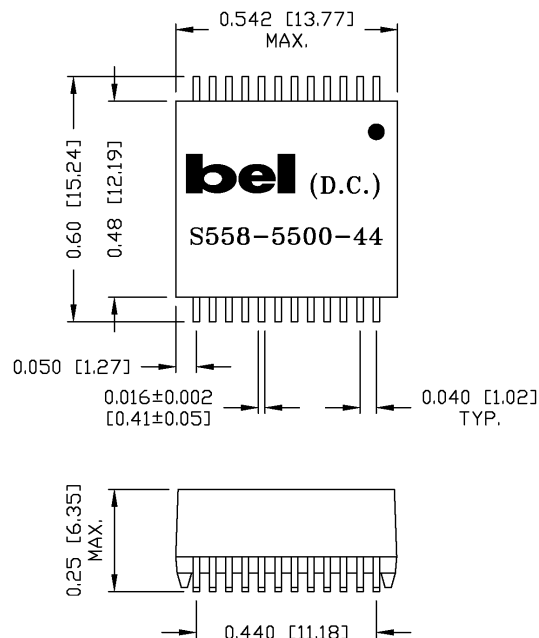


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RoHS
 2002/95/EC



SUGGESTED PCB PAD LAYOUT



NOTES:

1. STANDARD MARKING REFER TO DOC. HAND-WORK-04.
2. PACKAGE CODE: "QSS001".

ORIGINATED BY	DATE	TITLE	PART NO. / DRAWING NO.	STANDARD DIM.	[] METRIC DIM. AS REFERENCE	
HD	10-26-05	MECHANICAL DRAWING S558-5500-44	X558-5500-44	TOL. IN INCH	UNIT : INCH [mm]	REV. : A
DRAWN BY	DATE		FILE NAME	.X	SCALE : N/A	SIZE : A4
DQ Chen	10-26-05		X558550044A.DWG	.XX ±0.01 .XXX ±0.005	SCALE : N/A	PAGE : 3

